

350PEQ SERIES

520 Amp RMS, ∇ DI-VERGENCE* Gate, Hockey Puk, Inverter SCRs

Major Ratings and Characteristics

	350PEQ_W	Units
I_T (RMS)	520	A
I_T (AV)	330	A
@ max. T_C	70	$^{\circ}C$
I_{TSM}	@ 50 Hz	6200
	@ 60 Hz	6500
i^2t	@ 50 Hz	193,000
	@ 60 Hz	176,000
I_{GT}	150	mA
dv/dt	400	V/ μs
di/dt	1200	A/ μs
t_q (max.) ①	10 - 20	μs
T_J	-40 to 125	$^{\circ}C$
V_{DRM} , V_{RRM} Range	500 - 1200	V

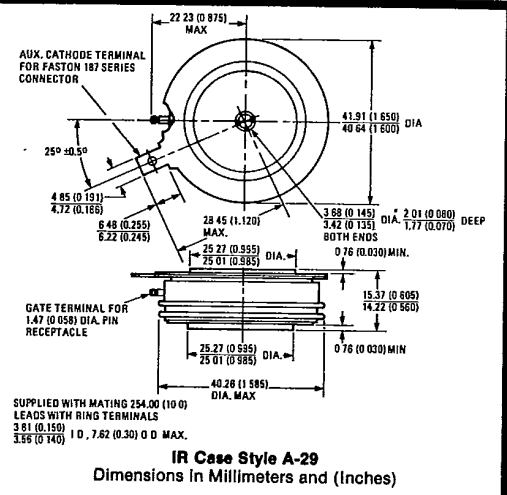
① Refer to the Electrical Specifications Table in this data sheet for specific turn-off times.

Description/Features

The PEQ Series high current, pressure assembled SCRs are designed for power switching at high voltages and high frequencies. The advanced Δ DI-VERGENCE* Gate geometry provides fast turn-on and high di/dt.

- Advanced Δ DI-VERGENCE* Gate geometry provides fast turn-on and high di/dt
- Very low switching losses at high frequency
- Short maximum guaranteed turn-off times
- Available up to 1,800 Volts
- Designed for power switching applications up to 5 KHz

* Divergence is the net outward rate of flow per unit of volume and time of electric charge, in this use.



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VOLTAGE RATINGS (Applied gate voltage zero or negative)

Part Number	V_{RRM} - Max. Repetitive Peak Reverse Voltage (V)	V_{DRM} - Max. Repetitive Peak Off-State Voltage (V) ^①	V_{RSM} - Max. Non-Repetitive Peak Reverse Voltage (V) ($t_p \leq 5$ ms)	I_{RM}, I_{DM} - Max. Peak Reverse and Off-State Current (mA) ^① ^②
	$T_J = -40^\circ\text{C}$ to 125°C	$T_J = -40^\circ\text{C}$ to 125°C	$T_J = 25^\circ\text{C}$ to 125°C	
350PEQ50W	500	500	600	20
350PEQ60W	600	600	700	20
350PEQ70W	700	700	800	20
350PEQ80W	800	800	900	20
350PEQ90W	900	900	1000	20
350PEQ100W	1000	1000	1100	20
350PEQ110W	1100	1100	1200	20
350PEQ120W	1200	1200	1300	20

^① Units may be broken over non-repetitively in the off-state direction without damage if di/dt does not exceed $20 \text{ A}/\mu\text{s}$.

^② At rated $V_{RRM}, V_{DRM}, T_J = 125^\circ\text{C}$.

^③ Zero gate bias voltage, gate open circuited.

ELECTRICAL SPECIFICATIONS

		350PEQ	Units	Conditions
ON-STATE				
$I_{T(RMS)}$	Nominal RMS on-state current	520	A	-
$I_{T(AV)}$	Max. average on-state current	330	A	Max. $T_C = 70^\circ\text{C}$, 180° half sine wave conduction.
I_{TSM}	Max. peak one cycle, non-repetitive surge current	6200	A	Following any rated load condition, and with rated V_{RRM} applied, SCR turned fully on.
		6500		
		7400		
		7700		
I^2t	Max. I^2t capability for fusing	193,000	A^2s	Rated V_{RRM} following surge, initial $T_J = 125^\circ\text{C}$.
		176,000		
I^2t	Max. I^2t capability for individual device fusing	273,000	A^2s	V_{RRM} following surge = 0, initial $T_J = 125^\circ\text{C}$.
		249,000		
$I^2\sqrt{t}$	Max. $I^2\sqrt{t}$ capability for individual device fusing ^③	2,730,000	$A^2\sqrt{s}$	V_{RRM} following surge = 0, initial $T_J = 125^\circ\text{C}$.
V_{TM}	Max. peak on-state voltage	3.05	V	$T_J = 25^\circ\text{C}$, $I_{T(AV)} = 330\text{A}$ (1,037A peak).
I_H	Max. holding current	500	mA	$T_C = 25^\circ\text{C}$, anode supply = 22V, initial $I_T = 20\text{A}$.
BLOCKING				
dv/dt	Min. critical rate-of-rise of off-state voltage	400	$V/\mu\text{s}$	$T_J = 125^\circ\text{C}$, exponential to 100% rated V_{DRM} . Gate open circuited.
		1000		
SWITCHING				
t_d	Typical delay time	1.0	μs	$T_C = 25^\circ\text{C}$, $V_{DM} = \text{rated } V_{DRM}$, $I_T = 50\text{A}$ dc resistive circuit. Gate pulse 10V, 20Ω source, $t_p = 6 \mu\text{s}$, $t_r = 0.5 \mu\text{s}$.
di/dt	Max. non-repetitive rate of rise of turned-on current	1200	$A/\mu\text{s}$	$T_C = 125^\circ\text{C}$, $V_{DM} = \text{rated } V_{DRM}$, $I_{TM} = 2,400\text{A}$, 60 p/s, snubber $0.2 \mu\text{F}$, 15Ω . Gate pulse: 20V, 65Ω source, $t_p = 6 \mu\text{s}$, $t_r = 0.5 \mu\text{s}$.

^③ I^2t for time $t_x = I^2\sqrt{t} \cdot \sqrt{t_x}$.

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ELECTRICAL SPECIFICATIONS (Continued)

		350PEQ	Units	Conditions
SWITCHING (Continued)				
t_q	Max. turn-off time without feedback diode			$T_C = 125^\circ\text{C}$, $I_{TM} = 500\text{A}$, $di/dt = -25\text{A}/\mu\text{s}$, Min. V_R during turn-off interval = 50V, reapplied $dv/dt = 400\text{V}/\mu\text{s}$ linear to 80% of rated V_{DRM} . Gate bias: 0V, 100 Ω .
	350PEQ - W10	10	μs	
	350PEQ - W12	12		
	350PEQ - W15	15		
	350PEQ - W20	20		
$t_q(\text{diode})$	Typical turn-off time with feedback diode			$T_C = 125^\circ\text{C}$, $I_{TM} = 500\text{A}$, $di/dt = -25\text{A}/\mu\text{s}$, Min. V_R during turn-off interval = 1.5V, reapplied $dv/dt = 200\text{V}/\mu\text{s}$ linear to 80% of rated V_{DRM} . Gate bias: 0V, 100 Ω .
	350PEQ - W10	11	μs	
	350PEQ - W12	15		
	350PEQ - W15	17		
	350PEQ - W20	22		
Q_{RR}	Typical recovered charge	200	μC	$T_J = 125^\circ\text{C}$, $I_{TM} = 1,000\text{A}$, $di/dt = -100\text{A}/\mu\text{s}$.
TRIGGERING				
P_{GM}	Max. peak gate power	100	W	$t_p = 5\text{ms}$
$P_{G(AV)}$	Max. average gate power	3.0	W	
$+I_{GM}$	Max. peak positive gate current	10	A	
$+V_{GM}$	Max. peak positive gate voltage	40	V	
$-V_{GM}$	Max. peak negative gate voltage	5.0	V	
I_{GT}	Max. required DC gate current to trigger	350	mA	$T_C = -40^\circ\text{C}$
		150		$T_C = 25^\circ\text{C}$
		100		$T_C = 125^\circ\text{C}$
	Typical DC gate current to trigger	75	mA	$T_C = 25^\circ\text{C}$
V_{GT}	Max. required DC gate voltage to trigger	5.0	V	$T_C = -40^\circ\text{C}$
		3.0		$T_C = 25^\circ\text{C}$
		1.25		$T_C = 25^\circ\text{C}$
	Typical DC gate voltage to trigger	1.25	V	$T_C = 25^\circ\text{C}$
V_{GD}	Max. DC gate voltage not to trigger	0.25	V	$T_C = 125^\circ\text{C}$. Max. gate current (or voltage) not to trigger is the maximum value which will not trigger any unit with rated V_{DRM} anode-to-cathode.

THERMAL-MECHANICAL SPECIFICATIONS

T_J	Operating junction temperature range	-40 to 125	$^\circ\text{C}$	
T_{stg}	Storage temperature range	-40 to 150	$^\circ\text{C}$	
R_{thJC}	Max. internal thermal resistance, junction-to-case	0.048	deg. C/W	DC operation, double side cooled.
R_{thCS}	Thermal resistance, case-to-sink	0.040	deg. C/W	One pole piece to one heat dissipator. (Mounting surface smooth, flat and greased.)
F	Mounting force	8,900 \pm 10% (2,000 \pm 10%)	N (lbf)	
wt	Approximate weight	85 (3.0)	g (oz.)	
	Case Style	IR A-29		

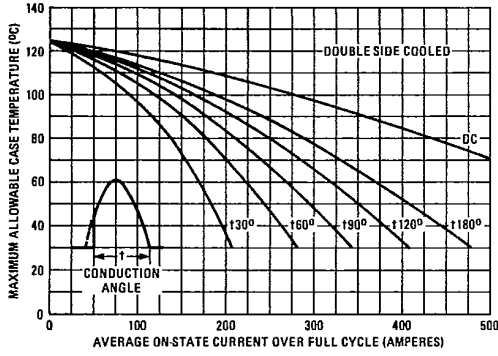


Fig. 1 – Maximum Allowable Case Temperature Vs Average On-State Current (Sinusoidal Current Waveform)

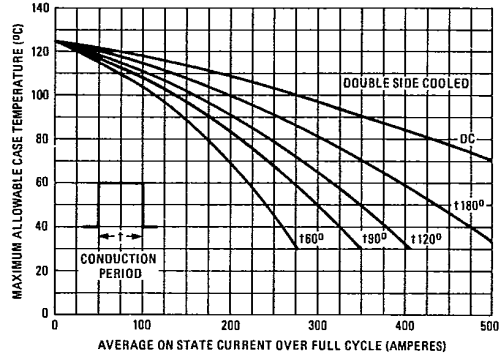


Fig. 2 – Maximum Allowable Case Temperature Vs Average On-State Current (Rectangular Current Waveform)

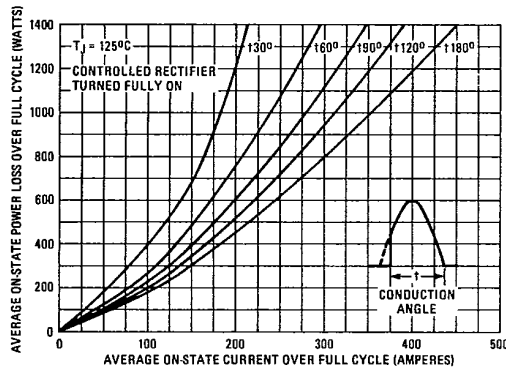


Fig. 3 – Maximum Low-Level On-State Power Loss Vs Average On-State Current (Sinusoidal Current Waveform)

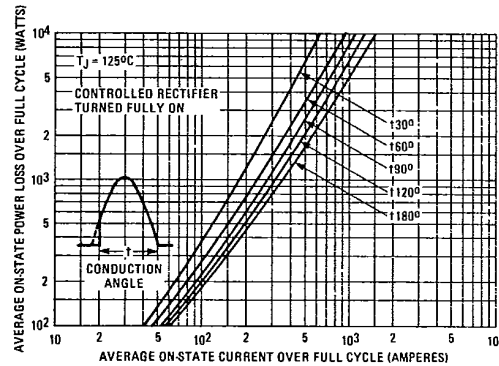
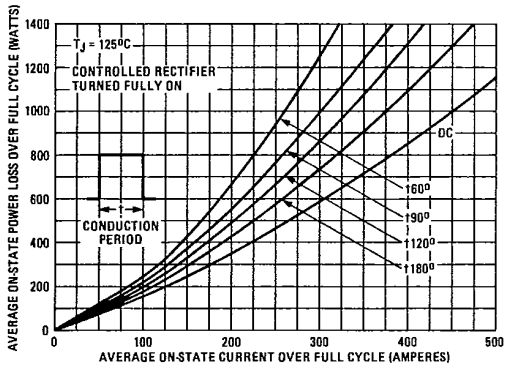


Fig. 4 – Maximum High-Level On-State Power Loss Vs Average On-State Current (Sinusoidal Current Waveform)



4 Fig. 5 – Maximum Low-Level On-State Power Loss Vs Average On-State Current (Rectangular Current Waveform)

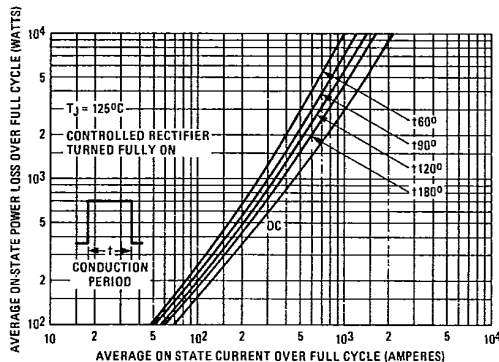


Fig. 6 – Maximum High-Level On-State Power Loss Vs Average On-State Current (Rectangular Current Waveform)

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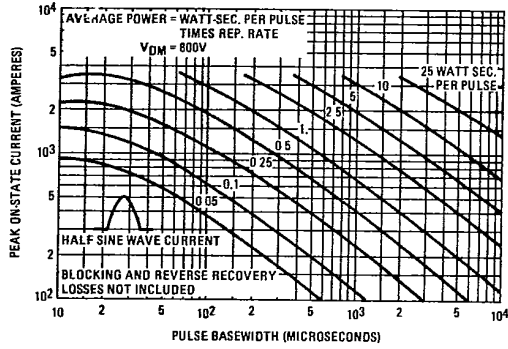


Fig. 7 - Maximum Energy Per Pulse for Half Sine Wave On-State Current

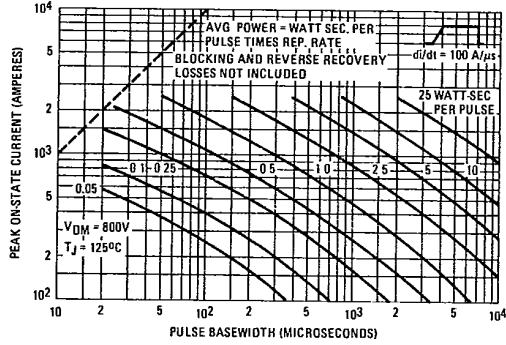


Fig. 8 - Maximum Energy Per Pulse for Trapezoidal On-State Current ($di/dt = 100 A/\mu s$)

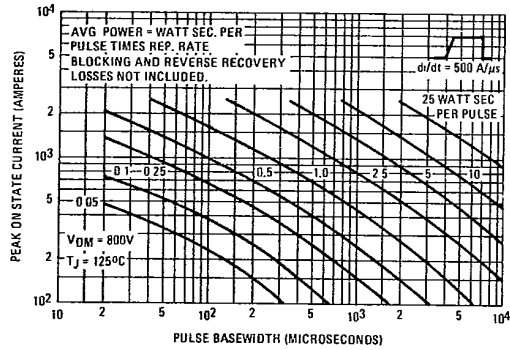


Fig. 9 - Maximum Energy Per Pulse for Trapezoidal On-State Current ($di/dt = 500 A/\mu s$)

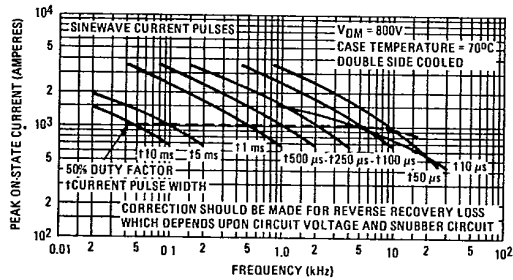


Fig. 10 - Maximum Allowable Peak On-State Current Vs Frequency (Sinewave Current Pulses - $di/dt = 100 A/\mu s$)

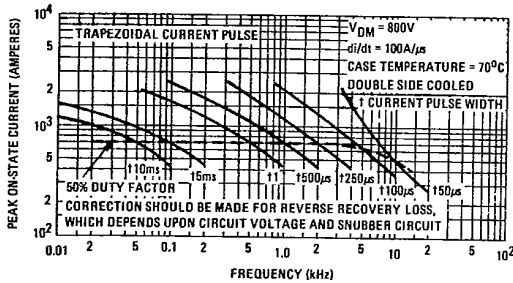


Fig. 11 - Maximum Allowable Peak On-State Current Vs Frequency (Trapezoidal Current Pulses)

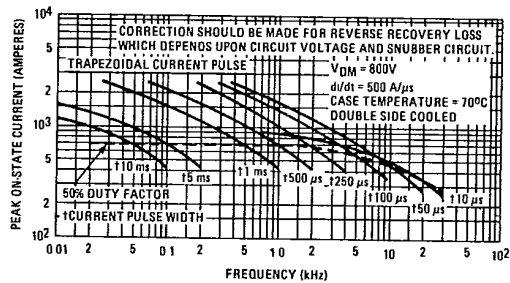


Fig. 12 - Maximum Allowable Peak On-State Current Vs Frequency (Trapezoidal Current Pulses - $di/dt = 500 A/\mu s$)

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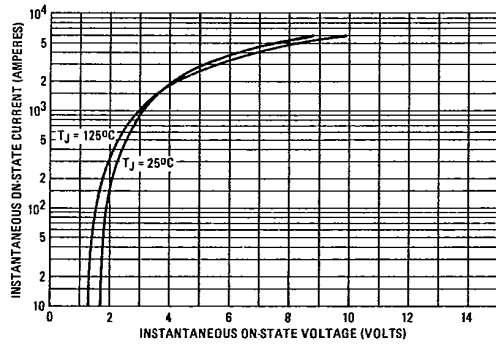
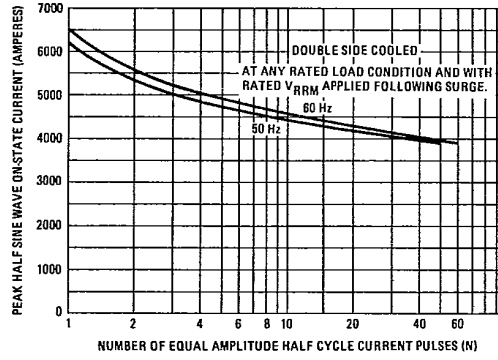


Fig. 13 - Maximum Instantaneous On-State Voltage Vs Instantaneous On-State Current



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Fig. 14 - Maximum Non-Repetitive Surge Current Vs Number of Current Pulses

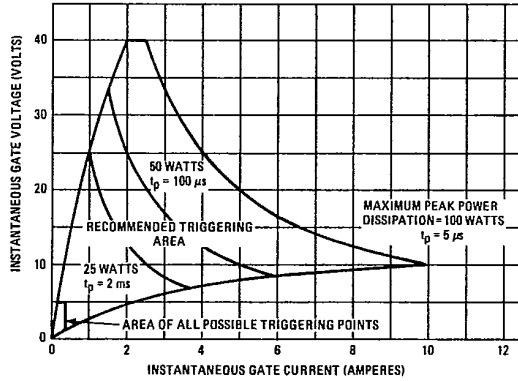


Fig. 15 - Gate Characteristics

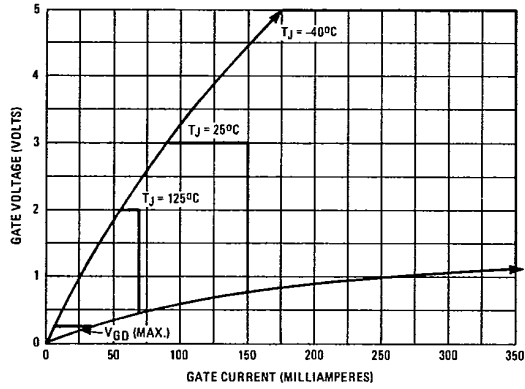


Fig. 15A - Areas of All Possible Triggering Points

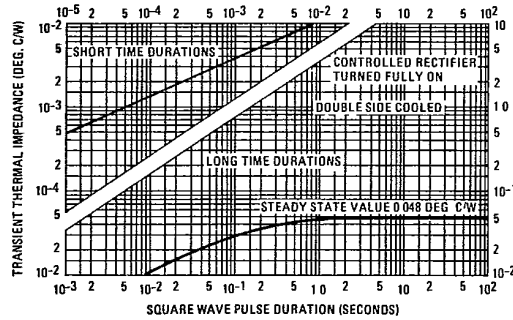


Fig. 16 - Transient Thermal Impedance, Junction-to-Case, Vs Square Wave Pulse Duration

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